

Claims

[c1] What is claimed is:

1. A wafer holder for semiconductor manufacturing equipment, the wafer holder having a surface for carrying wafers and comprising a layer of electrical circuitry composed of one or more sinter laminae, formed either on the face or in the interior of the wafer holder, said circuit layer having porosity in that pores are present therein.

[c2] 2. A wafer holder as set forth in claim 1, wherein: said circuit layer is as its main constituent one or more metals selected from tungsten, molybdenum and tantalum; and said porosity is 0.1% or more.

[c3] 3. A wafer holder as set forth in claim 1, wherein: said circuit layer is as its main constituent one or more metals selected from silver, vanadium and platinum; and said porosity is 2% or more.

[c4] 4. A wafer holder as set forth in claim 2, wherein said electrical circuitry any of an electrode circuit for an electrostatic chuck, a resistive-heating-element circuit, an

RF-power electrode circuit, and a high-voltage-generating electrode circuit.

- [c5] 5. A wafer holder as set forth in claim 3, wherein said electrical circuitry any of an electrode circuit for an electrostatic chuck, a resistive-heating-element circuit, an RF-power electrode circuit, and a high-voltage-generating electrode circuit.
- [c6] 6. Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 1 is installed.
- [c7] 7. Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 2 is installed.
- [c8] 8. Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 3 is installed.
- [c9] 9. Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 4 is installed.
- [c10] 10. Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 5 is installed.